

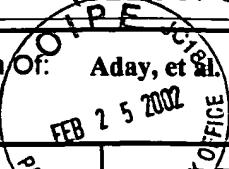
## TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT

(Under 37 CFR 1.97(b) or 1.97(c))

Docket No.  
BUR920010167US1

21-02

In Re Application Of: Aday, et al.

Serial No.  
09/683,733Filing Date  
02/07/02

Examiner

Group Art Unit

Title: CUSTOM PRICING SYSTEM AND METHOD

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Address to:

MAR 08 2002

Assistant Commissioner for Patents  
Washington, D.C. 20231

Technology Center 2100

## 37 CFR 1.97(b)

- The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application other than a continued prosecution application under 37 CFR 1.53(d); within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; before the mailing of a first Office Action on the merits, or before the mailing of a first Office Action after the filing of a request for continued examination under 37 CFR 1.114.

## 37 CFR 1.97(c)

- The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(b), provided that the Information Disclosure Statement is filed before the mailing date of a Final Action under 37 CFR 1.113, a Notice of Allowance under 37 CFR 1.311, or an Action that otherwise closes prosecution in the application, and is accompanied by one of:

 the statement specified in 37 CFR 1.97(e);

OR

 the fee set forth in 37 CFR 1.17(p).

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT  
(Under 37 CFR 1.97(b) of 1.97(c))

Docket No.  
BUR920010167US1

In Re Application: Aday, et al.

FEB 25 2002

PTAB  
U.S. PATENT & TRADEMARK OFFICE

Serial No.

09/683,733

Filing Date

02/07/02

Examiner

Group Art Unit

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Payment of Fee

(Only complete if Applicant elects to pay the fee set forth in 37 CFR 1.17(p))

A check in the amount of \_\_\_\_\_ is attached.

The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No.09-0456 as described below. A duplicate copy of this sheet is enclosed.

Charge the amount of \_\_\_\_\_

Credit any overpayment.

Charge any additional fee required.

Certificate of Transmission by Facsimile\*

I certify that this document and authorization to charge deposit account is being facsimile transmitted to the United States Patent and Trademark Office (Fax. No. \_\_\_\_\_) on \_\_\_\_\_

(Date)

Signature

Typed or Printed Name of Person Signing Certificate

Certificate of Mailing by First Class Mail

I certify that this document and fee is being deposited on 02/12/02 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

*Pat Guillemette*

Signature of Person Mailing Correspondence

Pat Guillemette

Typed or Printed Name of Person Mailing Certificate

\*This certificate may only be used if paying by deposit account.

*Richard M. Kotulak*  
Signature

Richard M. Kotulak

Registration No. 27,712

International Business Machines Corporation

Intellectual Property Law - Mail 972E

1000 River Street

Essex Junction, VT 05452

Dated: 2/11/02

CC:

ET693515872US



IBM Docket #:BUR920010167US1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Aday et al. : Date: January 4, 2002

Serial Number: Concurrent : Group Art Unit:

Filed: Concurrent : Examiner:

Title: Custom Pricing System and Method : IBM CORPORATION  
Intellectual Property Law  
: 1000 River Street, 972E  
Essex Junction, Vermont 05452

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MAR 08 2002

Technology Center 2100

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INFORMATION DISCLOSURE STATEMENT (IDS) UNDER 37 CFR 1.97

Commissioner For Patents  
Washington, D. C. 20231

Dear Sir:

The attached Form PTO-1449, and any attached foreign patent office search report, provides a listing of information which may be relevant to the subject application. This IDS is not intended as a representation that better art is not available, nor that the information provided is prior art.

This IDS is submitted under:

X 37 CFR 1.97(b) - No Fee.

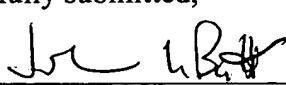
       37 CFR 1.97(c) - No Fee. Each item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application. This communication is dated \_\_\_\_\_, which is not more than 3 months prior to the mailing of this statement.

       37 CFR 1.97(c) - Fee.

       37 CFR 1.97(d) - Fee, Certification & Petition.

The Commissioner is authorized to charge payments of any associated fees required under 37 CFR 1.17(p) and (i) (1) to Deposit Account No. 09-0456.

Respectfully submitted,

By:   
John W. LaBatt  
Registration No. 48,301  
Telephone No.: (518) 449-0044

<b>INFORMATION DISCLOSURE CITATION</b> <i>(Use several sheets if necessary)</i>				Docket Number (Optional) <b>BUR920010167US1</b>	Application Number <b>09/683,733</b>			
				Applicant(s) <b>Aday et al.</b>				
				Filing Date <b>03/07/02</b>	Group Art Unit			
<b>U.S. PATENT DOCUMENTS</b>								
*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
		US20010023418A1	09/2001	Suzuki et al.				
		US 6,249,776 B1	06/2001	Bajuk et al.				
		5,960,417	09/1999	Pan et al.				
<b>FOREIGN PATENT DOCUMENTS</b>								
	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO
<b>OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)</b>								
		P. K. Nag, W. Maly, and H. J. Jacobs, "Simulation of Yield/Cost Learning Curves with Y4," IEEE Transactions on Semiconductor Manufacturing, vol. 10, no. 2, pp. 256 - 266, May 1997.						
		R. Ross, J. Bailey, N. Atchison, and M. Effron, "A Comprehensive Sequential Yield Analysis Methodology and the Financial Payback for Higher Yields," 1999 IEEE/SEMI Advanced Semiconductor Manufacturing Conference, pp. 80-86, 1999.						
EXAMINER				DATE CONSIDERED				
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.								

<b>INFORMATION DISCLOSURE CITATION</b> <i>(Use several sheets if necessary)</i>		Docket Number (Optional) <b>BUR920010167US1</b>	Application Number <b>09/683,733</b>
		Applicant(s) <b>Aday et al.</b>	Filing Date <b>02/07/02</b>
*EXAMINER INITIAL	<b>OTHER DOCUMENTS &amp; TRADEMARKS</b> (Including Author, Title, Date, Pertinent Pages, Etc.)		
	C. A. Moritz, D. Yeung, and A. Agarwal, "SimpleFit: A Framework for Analyzing Design Trade-Offs in Raw Architectures," IEEE Transactions on Parallel and Distributed Systems, vol. 12, no. 7, pp. 730-742, July 2001		
	G. A. Allan and A. J. Walton, "Fast Yield Prediction for Accurate Costing of ICs," 1996 Innovative Systems in Silicon Conference, Session 8: Yield & Testing, pp. 279-287, 1996.		
	nTool Solutions, <a href="http://www.ntool.com/ntool/Solutions/Cps/Ndiesizer/Ndiesizer.html">http://www.ntool.com/ntool/Solutions/Cps/Ndiesizer/Ndiesizer.html</a> , printed October 8, 2001.		
	"UMC UNVEILS CHIPSIZER: Online Tool Estimates Die Size and Silicon Cost," <a href="http://www.umc.com/english/news/20001030.asp">http://www.umc.com/english/news/20001030.asp</a> , October 30, 2000.		
	"UMC Chipsizer" <a href="http://eproject.umc.com/dse/">http://eproject.umc.com/dse/</a> , printed October 8, 2001.		
	D. N. Maynard, R. J. Rosner, M. L. Kerbaugh, R. A. Hamilton, J. R. Bentlage, and C. A. Boye, "Wafer Line Productivity Optimization in a Multi-Technology Multi-Part-Number Fabricator," 1998 IEEE/SEMI Advanced Semiconductor Manufacturing Conference, pp. 34-42, 1998.		
			
EXAMINER		DATE CONSIDERED	

**\*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.**